

## • Post CMP Cleaning

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### • Cleaner 428

#### HighLights :

- \* Compact Design
- \* Single Wafer Handling
- \* R&D Application
- \* Reliable Performance

**This Unique Post CMP Wafer Cleaner is Integrated with Two Double Brush Stations with Compact Design for Small Footprint and Versatility of Cleaning (4"~8") Wafers.**

## Specifications

- **Application Wafer Size** : 100, 150 and 200 mm
- **Construction** : Input Spray Cleaning, Two Double Side Brush Cleaning and Spin Rinse Dry  
(Option : Separated QDR)
- **Cleaner Size** :  $\Phi$  64(OD)  $\Phi$  32(ID) 126(L)mm
- **Pre Cleaning Station** : DIW Knife \* High Pressure DIW Clean Using DIW Knife (In General, Panel Cleaning)
- **Roller Brush Station**
  - Chemical : NH<sub>4</sub>OH or DI NH<sub>4</sub>OH 0.5~4%
  - Brush Type : PVA Brush, Front and Backside of Wafer Cleaned at the Same Time
  - Brush Position Adjustment Angle +5, -5 Degree Adjustment Manual Adjustment
  - Rotating Speed :  $<\pm 5\%$  of full scale Range 30 ~ 200rpm
  - Chemical Supply : 4 Nozzle and Through the Brush
  - Available Chemical : 2 Chemical [NH<sub>4</sub>OH]
  - Chemical & DI Flow Rate :  $<\pm 5\%$  of full scale
- **Spin Station**
  - (Option : Mega Sonic Sweep)
  - Spin Speed : Max 3000 rpm
  - DI Rinse / N<sub>2</sub> Blow
- **Control**
  - Process : Manual Loading with Automatic Sequence, Wet-In / Dry-Out
  - LCD Monitor Touch Panel, Sequence Control PLC Type

